



Material Content Data Sheet



Sales Product Name		ICE2QS03		Issued		20. July 2018		
MA#		MA000980968						
Package		PG-DIP-8-13		Weight*		556.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.992	0.36	0.36	3578	3578
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		386	
	non noble metal	iron	7439-89-6	4.297	0.77		7718	
wire	non noble metal	copper	7440-50-8	174.475	31.34	32.16	313370	321570
	noble metal	gold	7440-57-5	0.220	0.04	0.04	395	395
	encapsulation	organic material	carbon black	1333-86-4	1.098	0.20		1972
encapsulation	plastics	epoxy resin	-	35.493	6.37		63748	
	inorganic material	silicondioxide	60676-86-0	329.313	59.14	65.71	591472	657192
leadfinish	non noble metal	tin	7440-31-5	7.496	1.35	1.35	13463	13463
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1429	1429
glue	plastics	epoxy resin	-	0.198	0.04		356	
	noble metal	silver	7440-22-4	1.123	0.20	0.24	2017	2373
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com